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TC 3700 MAIL ROOM

EXPRESS MAIL NO. EL 872037758 US

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Reissue Patent Application:

Applicants : Trung T. Doan and Gurtej S. Sandhu
Assignee: : Micron Technology, Inc.
Filed : December 19, 2001
For : POLISHING PAD REFURBISHER FOR IN SITU, REAL-TIME CONDITIONING
AND CLEANING OF A POLISHING PAD USED IN CHEMICAL-MECHANICAL
POLISHING OF MICROELECTRONIC SUBSTRATES
Docket No. : 500300.02

Corresponding Issued U.S. Patent:

Patent No. : 6,004,196
Issued : December 21, 1999
Application No. : 09/032,230
Filing Date : February 27, 1998
Examiner : William Hong
Art Unit : 3725

BOX REISSUE
Commissioner for Patents
Washington, D.C. 20231

PRELIMINARY AMENDMENT

Sir:

Please accept the request for a reissue of U.S. Patent No. 6,004,196, filed herewith. Prior to conducting the examination of the reissue claims, please amend the reissue application as follows:

Please add the following new claims 31-53:

- - 31. A pad refurbisher for refurbishing a polishing surface on a polishing pad used in chemical-mechanical polishing of a semiconductor wafer, comprising:

a body adapted for attachment to a wafer carrier of a chemical-mechanical polishing machine with the body having a face positioned proximate to a perimeter portion of the wafer carrier and facing the polishing surface of the polishing pad; and

a refurbishing element connected to the face of the body, the refurbishing element being adapted to engage the polishing surface substantially adjacent to the perimeter portion of the wafer carrier.

32. The pad refurbisher of claim 31 wherein the body is fixed to the wafer carrier.

33. The pad refurbisher of claim 1 wherein the body is slidably attached to the wafer carrier.

34. The pad refurbisher of claim 33, further comprising a linear actuator attached to the body, wherein the actuator independently moves the body with respect to the wafer carrier along an axis substantially normal to the polishing surface to selectively engage the refurbishing element with areas on the polishing surface in need of cleansing and to selectively disengage the refurbishing element from areas on the pad in adequate condition.

35. The pad refurbisher of claim 31 wherein the face is a distal face of the body defining a ring positioned radially outwardly from the perimeter of the wafer carrier.

36. The pad refurbisher of claim 31 wherein the body has a plurality of arcuate segments positioned radially outwardly from the perimeter of the wafer carrier, the arcuate segments being spaced apart from one another around the wafer carrier and each arcuate segment having a distal face facing generally towards the polishing surface of the polishing pad.

37. The pad refurbisher of claim 31 wherein the refurbishing element is a brush comprising a plurality of bristles extending downwardly from the face towards the polishing surface, the bristles engaging the polishing surface to clean waste particles from the pad.

38. The pad refurbisher of claim 31 wherein the refurbishing element is a pad conditioner that removes a layer of pad material from polishing surface of the pad to form a new polishing surface on the polishing pad.

39. The pad refurbisher of claim 38 wherein the pad conditioner comprises a pad with a plurality of embedded diamonds, the pad being connected to the distal surface of the body.

40. The pad refurbisher of claim 31 wherein the body has a first ring with a first refurbishing element and a second ring with a second refurbishing element, the first ring being positioned radially outwardly from the perimeter of the wafer carrier and the second ring being positioned radially outwardly from the first ring.

41. The pad refurbisher of claim 40 wherein the first refurbishing element is a pad cleaner and the second refurbishing element is a pad conditioner.

42. The pad refurbisher of claim 31 wherein the body is adapted to be symmetrically positioned about the center of the wafer carrier.

43. A polishing machine for chemical-mechanical polishing of a semiconductor wafer, comprising:

a platen having an upper surface;

a polishing pad positioned on the upper surface of the platen, the polishing pad having a polishing surface facing away from the platen;

a wafer carrier for carrying the wafer; and
a pad refurbisher having a body attached to the wafer carrier and having a
refurbishing element.

44. The polishing machine of claim 43 wherein the body comprises a face
positioned proximate to a perimeter portion of the wafer carrier and facing generally towards the
polishing surface.

45. The polishing machine of claim 44 wherein the refurbishing element is
connected to the face, and wherein the body being attached to the wafer carrier so that the body
and refurbishing element travel with the wafer carrier as the wafer carrier moves with respect to
the polishing pad, and wherein the refurbishing element engages the polishing surface
substantially adjacent to the perimeter portion of the wafer carrier while the wafer carrier moves
the wafer over the polishing surface.

46. The polishing machine of claim 43 wherein the body is fixed to the wafer
carrier.

47. A method for refurbishing a polishing pad, comprising the steps of:
providing a pad refurbisher attached to a wafer carrier, the pad refurbisher having
a refurbishing element;

selectively engaging the pad refurbishing element with the polishing pad; and
moving at least one of the wafer carrier and the polishing pad with respect to the
other to pass the refurbishing element across the polishing pad.

48. The method of claim 47 wherein selectively engaging comprises
selectively lowering the refurbishing element towards the polishing pad while the wafer carrier
presses a wafer against the polishing pad and moves the wafer over the polishing pad to polish
the wafer.

49. The method of claim 47 further comprising selectively disengaging the refurbishing element from the pad.

50. The method of claim 49 wherein the refurbishing element is selectively disengaged from relatively unused portions of the polishing pad not having accumulations of waste matter.

51. The method of claim 47 wherein the selectively engaging comprises lowering the wafer carrier until the refurbishing element and a wafer abut the polishing pad.

52. The method of claim 47 wherein the refurbishing element is selectively engaged with deteriorated portions of the polishing pad with accumulations of waste matter.

53. The method of claim 47 wherein the refurbishing element is selectively engaged and disengaged from the polishing pad as a function of the use of portions of the pad. - -

REMARKS

Consideration of this reissue application in view of the above amendments and following remarks is respectfully requested. Applicant is requesting reissue on the basis that the '196 patent is, through error without any deceptive intention, deemed wholly or partially inoperative by reason of the patentee claiming less than he had a right to claim in the '196 patent, as will be set forth in more detail in a reissue declaration to be submitted in the present application. For example, claim 1 of the '196 patent recites the limitation "wherein the body is movably attached to the wafer carrier" and the body need not be so movably attached. Moreover, applicant has a right to claims of varying scopes to provide a hedge against any of the issued claims being found invalid and to cover a broader range of infringing devices. The assignee

offers to surrender the '196 patent once the Examiner has indicated the allowability of all claims associated with this reissue application. The assignee is requesting a reissue of the '196 patent for the invention as disclosed in the '196 patent and claimed in issued claims 1-30 and new claims 31-53.

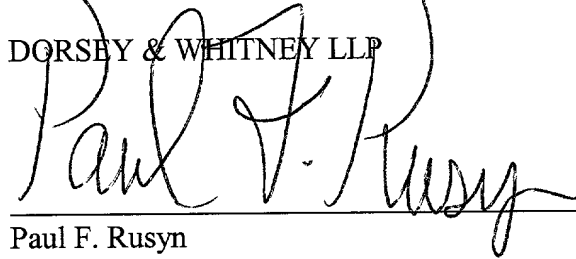
No new matter has been introduced into this application for reissue.

Applicant believes claims 1-53 are in condition for allowance and respectfully requests such action.

If there are any matters that can be handled in a telephone conversation, the Examiner is encouraged to contact Mr. Rusyn at (206) 903-8823.

Respectfully submitted,

DORSEY & WHITNEY LLP

A handwritten signature in black ink, reading "Paul F. Rusyn", written over a horizontal line.

Paul F. Rusyn

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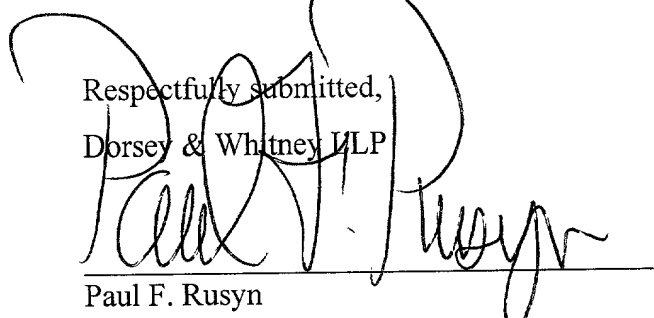
BOX REISSUE
 Commissioner for Patents
 Washington, DC 20231

FILING FORMAL DRAWINGS IN REISSUE APPLICATION

Sir:

Enclosed are the drawings from the original file of U.S. Patent No. 09/032,230 to be used for the reissue application of U.S. Patent No. 6,004,196. There are no changes in the drawings for the reissue application.

Respectfully submitted,
 Dorsey & Whitney LLP


 Paul F. Rusyn
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Enclosures:

Five (5) Sheets of Drawings, Figures 1-6

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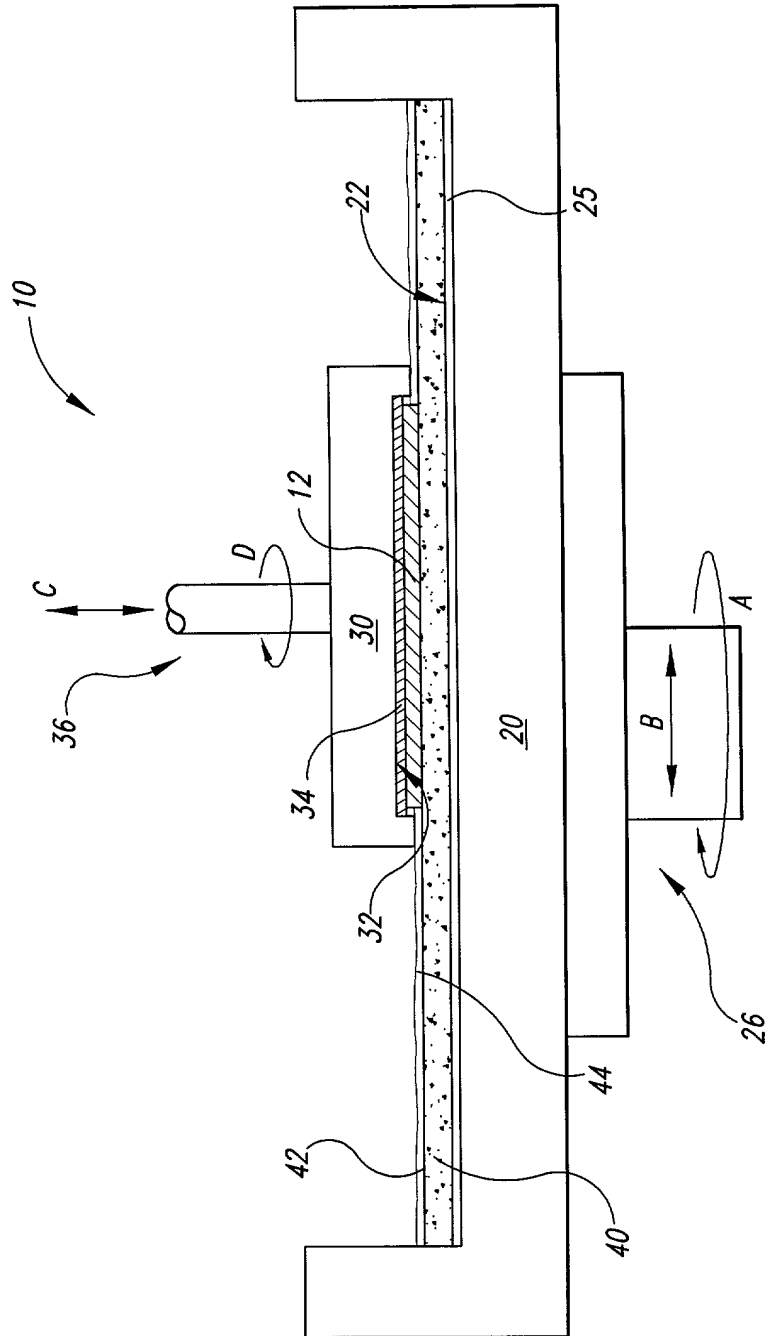
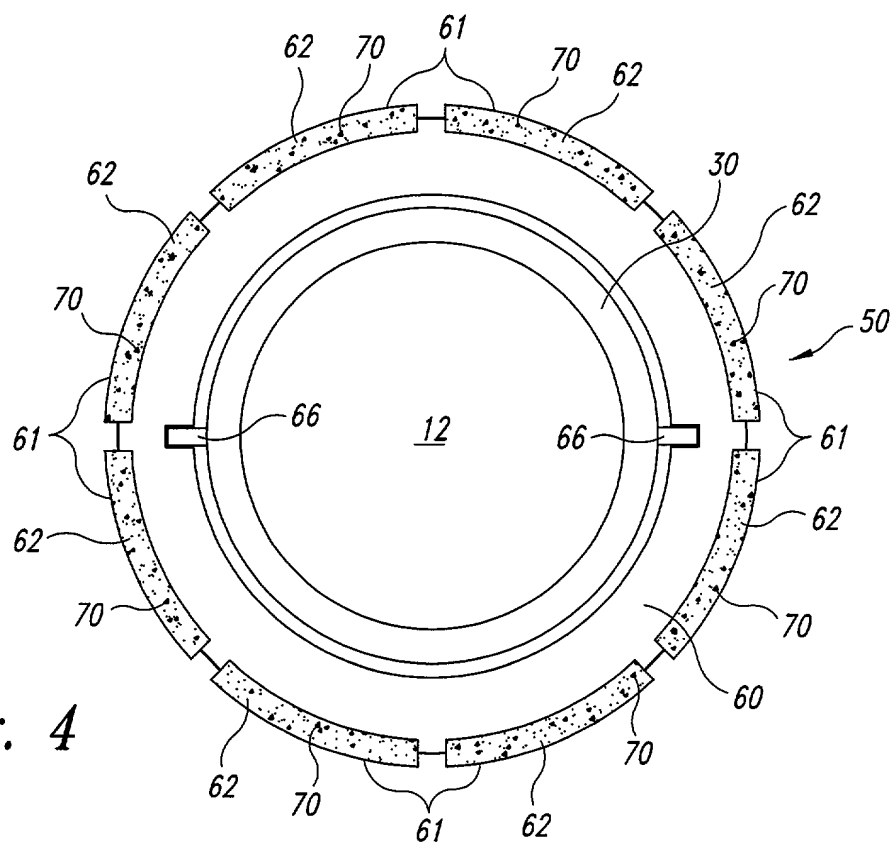
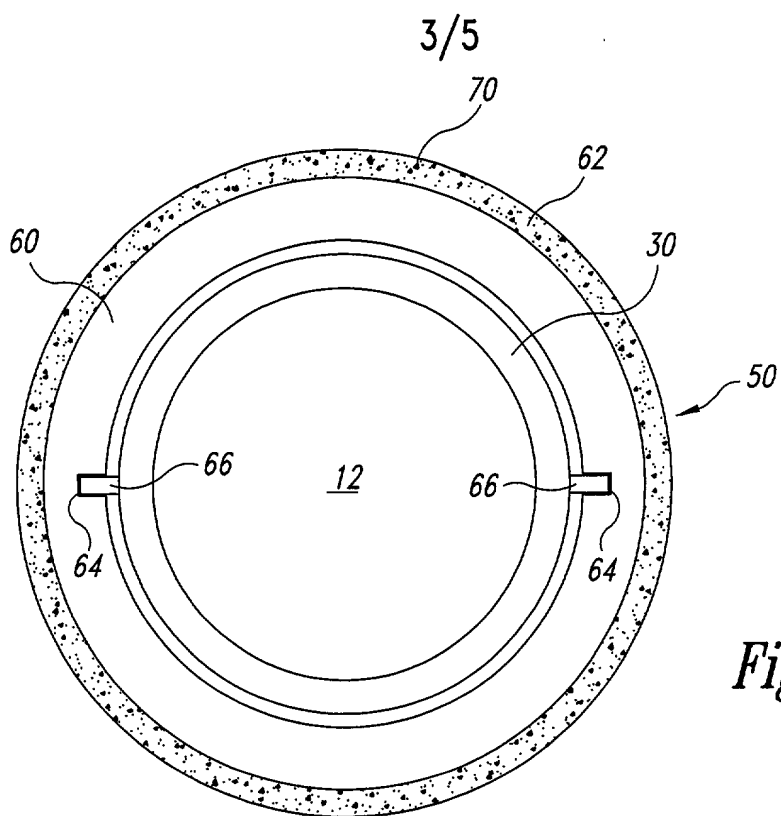


Fig. 1
(Prior Art)



Year	Age	Sex	Location	Species	Number	Percentage
1970	10	M	1000	1000	1000	1000
1971	11	F	1100	1100	1100	1100
1972	12	M	1200	1200	1200	1200
1973	13	F	1300	1300	1300	1300
1974	14	M	1400	1400	1400	1400
1975	15	F	1500	1500	1500	1500
1976	16	M	1600	1600	1600	1600
1977	17	F	1700	1700	1700	1700
1978	18	M	1800	1800	1800	1800
1979	19	F	1900	1900	1900	1900
1980	20	M	2000	2000	2000	2000
1981	21	F	2100	2100	2100	2100
1982	22	M	2200	2200	2200	2200
1983	23	F	2300	2300	2300	2300
1984	24	M	2400	2400	2400	2400
1985	25	F	2500	2500	2500	2500
1986	26	M	2600	2600	2600	2600
1987	27	F	2700	2700	2700	2700
1988	28	M	2800	2800	2800	2800
1989	29	F	2900	2900	2900	2900
1990	30	M	3000	3000	3000	3000
1991	31	F	3100	3100	3100	3100
1992	32	M	3200	3200	3200	3200
1993	33	F	3300	3300	3300	3300
1994	34	M	3400	3400	3400	3400
1995	35	F	3500	3500	3500	3500
1996	36	M	3600	3600	3600	3600
1997	37	F	3700	3700	3700	3700
1998	38	M	3800	3800	3800	3800
1999	39	F	3900	3900	3900	3900
2000	40	M	4000	4000	4000	4000
2001	41	F	4100	4100	4100	4100
2002	42	M	4200	4200	4200	4200
2003	43	F	4300	4300	4300	4300
2004	44	M	4400	4400	4400	4400
2005	45	F	4500	4500	4500	4500
2006	46	M	4600	4600	4600	4600
2007	47	F	4700	4700	4700	4700
2008	48	M	4800	4800	4800	4800
2009	49	F	4900	4900	4900	4900
2010	50	M	5000	5000	5000	5000
2011	51	F	5100	5100	5100	5100
2012	52	M	5200	5200	5200	5200
2013	53	F	5300	5300	5300	5300
2014	54	M	5400	5400	5400	5400
2015	55	F	5500	5500	5500	5500
2016	56	M	5600	5600	5600	5600
2017	57	F	5700	5700	5700	5700
2018	58	M	5800	5800	5800	5800
2019	59	F	5900	5900	5900	5900
2020	60	M	6000	6000	6000	6000
2021	61	F	6100	6100	6100	6100
2022	62	M	6200	6200	6200	6200
2023	63	F	6300	6300	6300	6300
2024	64	M	6400	6400	6400	6400
2025	65	F	6500	6500	6500	6500
2026	66	M	6600	6600		



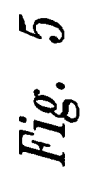


Fig. 5

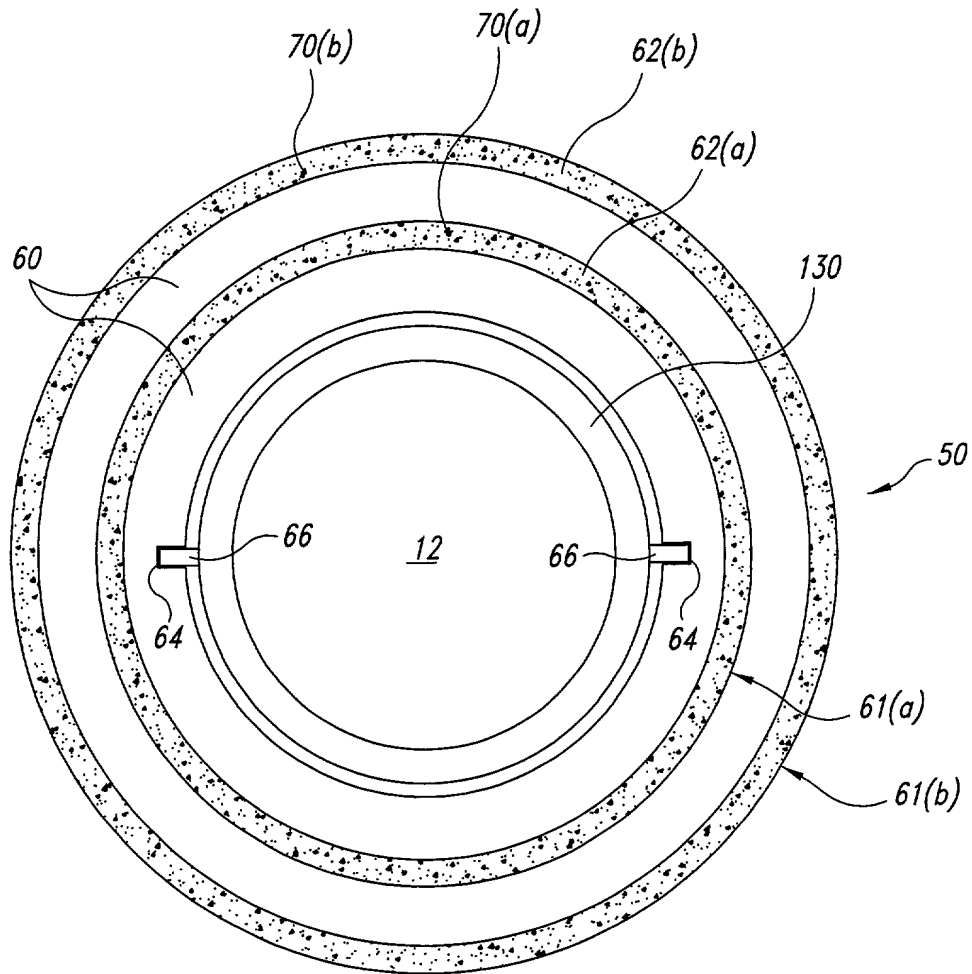


Fig. 6